

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Currently amended): ~~A method of testing in a test system comprising a tester and a test station, said method comprising:~~ The method of claim 56, wherein

the transmitting step comprises transmitting test data wirelessly from said tester to said test station, said test data representing a plurality of tests for testing an electronic device; and

the running step comprises testing said electronic device by running said plurality of tests on said electric device at said test station.

Claim 2 (Original): The method of claim 1 further comprising:

transmitting results of said testing wirelessly from said test station to said tester.

Claim 3 (Original): The method of claim 1, wherein said step of testing further comprises testing a plurality of electronic devices at said test station using said transmitted test data.

Claim 4 (Previously presented): The method of claim 1, wherein said test data comprises commands and said step of testing an electronic device comprises said test station executing said commands and thereby running said plurality of tests on said electronic device.

Claim 5 (Previously presented): The method of claim 4, wherein said electronic device comprises self-test circuitry and said step of executing commands comprises said test station initiating operation of said self-test circuitry.

Claim 6 (Previously presented): The method of claim 1, wherein said test system further comprises a plurality of test stations, and said step of transmitting test data comprises transmitting test data to at least two of said test stations.

Claim 7 (Previously presented): The method of claim 6, wherein test data transmitted to each of said at least two test stations is the same.

Claim 8 (Original): The method of claim 6, wherein test data transmitted to at least one of said test stations is different than test data transmitted to another of said test stations.

Claim 9 (Previously presented): The method of claim 6, wherein said step of testing comprises testing at each of said at least two test stations an electronics device at said test station using test data transmitted to said test station.

Claim 10 (Previously presented): The method of claim 9 further comprising transmitting from each of said at least two test stations results of testing said electronic device at said test station.

Claim 11 (Original): The method of claim 1 further comprising adding another test station to said test system.

Claim 12 (Original): The method of claim 11, wherein said step of adding another test station comprises said other test station transmitting wirelessly to said tester a request to be added to said test system.

Claim 13 (Original): The method of claim 1, wherein:

- said test system comprises a plurality of testers,
- said step of transmitting test data comprises a first tester of said plurality of testers transmitting first test data to said test station;
- said step of testing an electronic device comprises performing a first test on said electronic device in accordance with said first test data;
- said method further comprising
 - transmitting second test data wirelessly from a second tester of said plurality of testers to said test station; and
 - performing a second test on said electronic device at said test station in accordance with said second test data.

Claim 14 (Original): The method of claim 13, wherein said first test and said second test are different tests.

Claim 15 (Original): The method of claim 13, wherein a plurality of said electronic devices are disposed at said test station, and said first test is performed on a first subset of said plurality of electronic devices, and said second test is performed on a second subset of said plurality of electronic devices.

Claim 16 (Original): The method of claim 1, wherein said test station comprises a prober and said electronic device comprises a semiconductor wafer.

Claim 17 (Original): The method of claim 1, wherein said electronic device comprises a packaged semiconductor die.

Claim 18 (Original): The method of claim 1, wherein said electronic device comprises a singulated, unpackaged semiconductor die.

Claim 19 (Original): The method of claim 1, wherein said electronic device comprises a multi-chip module.

Claim 20 (Previously presented): A tester comprising:

initiating means for wirelessly initiating testing of an electronic device at a test station, wherein said testing comprises running a plurality of tests on said electronic device at said test station; and

receiving means for wirelessly receiving results of said testing from said test station.

Claim 21 (Original): The tester of claim 20, wherein said initiating means further comprises means for initiating testing of a plurality of electronic devices at said test station.

Claim 22 (Original): The tester of claim 20, wherein:

said initiating means further comprises means for initiating testing of an electronic device at each of a plurality of test stations; and

said receiving means further comprises means for receiving results of said testing from each of said test stations.

Claim 23 (Previously presented): The tester of claim 20 further comprising means for maintaining an identification of a plurality of test stations, wherein:

said initiating means further comprises means for initiating testing of an electronic device at each of said at least two test stations; and

said receiving means further comprises means for receiving results of said testing from each of said at least two test stations.

Claim 24 (Original): The tester of claim 23 further comprising adding means for adding an additional test station to said plurality of test stations.

Claim 25 (Original): The tester of claim 24, wherein said adding means adds said additional test station after said initiating means initiates testing of an electronic device at least one of said plurality of test stations but before said receiving means receives results of said testing of said electronic device at said at least one of said plurality of test stations.

Claim 26 (Original): The tester of claim 24 further comprising means for removing one of said test stations from said plurality of test stations.

Claim 27 (Original): The tester of claim 20 further comprising means for signaling another tester that results of testing have been received from said test station.

Claim 28 (Original): The tester of claim 20 further comprising means for receiving a signal from another tester that testing of said electronic device by said other tester is completed, wherein said initiating means initiates said testing in response to said signal from said other tester.

Claim 29 (Original): The tester of claim 20, wherein said test station comprises a prober and said electronic device comprises an unsingulated semiconductor wafer.

Claim 30 (Original): The tester of claim 20, wherein said electronic device comprises a packaged semiconductor die.

Claim 31 (Original): The tester of claim 20, wherein said electronic device comprises a singulated, unpackaged semiconductor die.

Claim 32 (Original): The tester of claim 20, wherein said electronic device comprises a multi-chip module.

Claim 33 (Previously presented): A test station comprising:

receiving means for wirelessly receiving test data from a tester, said test data representing a plurality of tests for testing an electronic device; and

testing means for testing said electronic device by running said plurality of tests on said electronic device .

Claim 34 (Original): The test station of claim 33 further comprising means for wirelessly transmitting results of said testing to said tester.

Claim 35 (Original): The test station of 33, wherein said receiving means further comprises means for receiving test data from a plurality of testers.

Claim 36 (Original): The test station of claim 35, wherein said testing means comprises:

means for testing said electronic device in accordance with first test data received from a first tester of said plurality of testers; and

means for testing said electronic device in accordance with second test data received from a second tester of said plurality of testers.

Claim 37 (Original): The test station of claim 36 further comprising transmitting means for wirelessly transmitting to said first tester results of said testing in accordance with said first test data and to said second tester results of said testing in accordance with said second test data.

Claim 38 (Previously presented): The test station of claim 35 further comprising a plurality of said electronic devices, wherein said testing means comprises:

means for testing a first subset of said plurality of electronic devices in accordance with test data received from a first tester of said plurality of testers; and

means for testing a second subset of said plurality of electronic devices in accordance with test data received from a second tester of said plurality of testers.

Claim 39 (Original): The test station of claim 33 further comprising means for wirelessly transmitting a request to said tester to configure the tester to transmit test data to said test station.

Claim 40 (Original): The test station of claim 33 further comprising means for wirelessly transmitting a request to said tester to configure the tester to stop transmitting test data to said test station.

Claim 41 (Original): The test station of claim 33, wherein said prober comprises a test station and said electronic device comprises an unsingulated semiconductor wafer.

Claim 42 (Original): The test station of claim 33, wherein said electronic device comprises a packaged semiconductor die.

Claim 43 (Original): The test station of claim 33, wherein said electronic device comprises a singulated, unpackaged semiconductor die.

Claim 44 (Original): The test station of claim 33, wherein said electronic device comprises a multi-chip module.

Claim 45 (Previously presented): The test station of claim 33, wherein said testing means comprises a digital storage device and a digital processor configured to control testing of said electronic device in accordance with instructions stored in said digital storage device.

Claim 46 (Previously presented): The test station of claim 33, wherein said test data comprises at least one test vector comprising data and locations to which said data is to be written.

Claim 47 (Previously presented): The test station of claim 46, wherein said locations comprise identifications of probes through which said test data is to be written to said electronic device.

Claim 48 (Previously presented): The tester of claim 20, wherein said initiating means comprises a digital storage device and a digital processor configured to operate in accordance with instructions stored in said digital storage device.

Claim 49 (Previously presented): The tester of claim 20, wherein said test data comprises at least one test vector comprising data and locations to which said data is to be written.

Claim 50 (Previously presented): The tester of claim 49, wherein said locations comprise identifications of probes through which said test data is to be written to said electronic device.

Claim 51 (Previously presented): The method of claim 1 wherein said testing step is performed under control of a digital processor configured to control testing of said electronic device in accordance with instructions stored in a digital storage device.

Claim 52 (Previously presented): The method of claim 1, wherein said test system comprises a plurality of test stations, and said transmitting step comprises transmitting test data from one tester to at least two of said test stations.

Claim 53 (Previously presented): The method of claim 1, wherein said test system comprises a plurality of testers, wherein said transmitting step comprises transmitting test data from at least two of said testers to one test station.

Claim 54 (Previously presented): The method of claim 1, wherein said test data comprises at least one test vector comprising data and locations to which said data is to be written.

Claim 55 (Previously presented): The method of claim 54, wherein said locations comprise identifications of probes through which said test data is to be written to said electronic device.

Claim 56 (Previously presented): A method of testing in a system comprising a tester and a test station, said method comprising:

transmitting a test directive wirelessly from said tester to said test station; and
running at said test station a test on said electric device in accordance with said test directive.

Claim 57 (Previously presented): The method of claim 56, wherein said test directive comprises a command, and said running step comprises said test station decoding said command.

Claim 58 (Previously presented): The method of claim 56, wherein said test directive comprises a command, and said running step comprises said test station executing said command and thereby running said test on said electronic device.

Claim 59 (Previously presented): The method of claim 56, wherein said test directive comprises a test vector comprising data and locations to which said data is to be written.

Claim 60 (Previously presented): The method of claim 59, wherein said locations comprise identifications of probes through which said test data is to be written to said electronic device.

Claim 61 (Previously presented): The method of claim 56, wherein:

said transmitting step comprises transmitting a plurality of test directive wirelessly from said tester to said test station; and

said running step comprises running at said test station a plurality of tests on said electric device in accordance with said test directives.